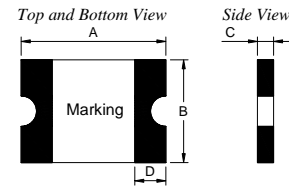


### 1、Physical Dimensions(size of 1812)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
MSMD200/12	4.37	4.73	3.07	3.41	0.60	1.00	0.30	T200



### 2、Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> (Max time to trip)		Pd <sub>typ</sub> (W)	R <sub>min</sub> (Ω)	R1 <sub>max</sub> (Ω)
					Current(A)	Time(S)			
MSMD200/12	2.00	4.00	12	100	8.0	3.00	1.2	0.020	0.080

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I<sub>max</sub>: Maximum fault current device can withstand without damage at rated voltage.

T<sub>trip</sub>: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

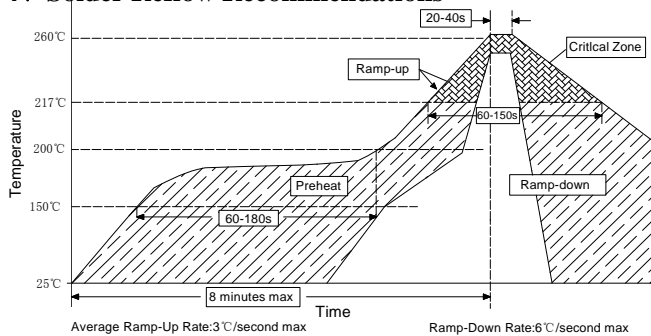
R1<sub>max</sub>: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

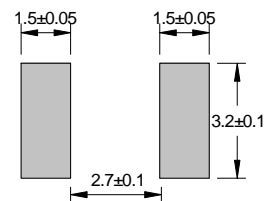
### 3、Thermal Derating

MSMD200/12	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	3.08	2.71	2.35	2.00	1.80	1.60	1.50	1.40	1.25
Trip Current(A)	6.16	5.42	4.70	4.00	3.60	3.20	3.00	2.80	2.50

### 4、Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### 5、Package Information

Packing quantity: 1500PCS/Reel

Note: Reel packaging per EIA-481-1 standard